



Warsaw University of Technology, Poland, 10.05.2019

Dear IEEE IES Students and Young Professionals (S&YP),

Thank you for your excellent contribution and congratulation! It is a great honor to announce the Awardees of the IES-SYPA competition for the **IEEE ELECTRIMACS 2019.**

Important note for the S&YP that applied for the IES-SYPA:

In this year for the **IEEE ELECTRIMACS'19** we have received **7** applications for the **IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE (IES-SYPA).** The average weighted score is **5.86.** We would like to announce **1 IES-SYPA** (recognition diploma plus up-to **USD 1000** travel costs reimbursement) recipient (see the table below).

	transaction	applicant	manuscript title	all authors
	136	VARECHA Patrik University of Žilina Slovak Republic patrik.varecha@fel.uniza.sk	Low-side MOSFET current sensing technique for Power Converters used in Automotive Applications	Patrik Varecha, Giacomo Scelba, Mario Cacciato, Matej Pacha, Pavol Makys

Mandatory requirements and important notes:

- I. Please take into account that IEEE IES must follow general rules of IEEE related with OFAC Sanctions Programs to learn more please see https://www.ieee.org/about/compliance/ofac/sanctions.html. For more details, you may ask The Legal and Compliance Department available to assist with reviewing any questions that you may have with respect to OFAC or other compliance matters and can be reached at compliance@ieee.org.
- II. You will have to be active during the conference as a volunteer. For tasks and more details, please contact Secretary of ELECTRIMACS at: electrimacs2019@unisa.it , Giovanni Petrone <gpetrone@unisa.it >, Walter Zamboni < wzamboni@unisa.it > Gen. Chairs ELECTRIMACS 2019 and to Marek Jasiński marek.jasinski@ieee.org.
- III. **Students** and **Young Professionals** must present their project in a 3-minutes speech (3Ms) accompanied by a 3-minute video clip and with hardware demonstration (if applicable).
- IV. You will receive the SYPA result by email from Marek Jasinski, and then, you will receive the full instruction on how to prepare that video and speech for 3Ms IES-SYPA Speech Video Session and the submission deadline from Hani Vahedi (hani.vahedi@ieee.org).
- V. Your video will be uploaded on IES YouTube Channel, Facebook Page, and IEEE Collabratec to be available during the conference. Important:
 - a. Please open an IEEE Collabratec account with your IEEE login information, and you will receive the information about how to join the IES-SYPA group.
 - b. Once your video is approved and uploaded to the IES YouTube, then you should post it to the IEEE Collabratec Group and to the Facebook event page.
- VI. Please be sure that during the conference <u>you should have your video available offline</u> and the hardware demonstration (if applicable).

(Time and place for 3Ms presentation will be announced by the General Chair of the Conference)

VII. The diplomas for the IES-Student Paper Travel Assistance (IES-SYPA) will be presented during the

(Time and place will be announced by the General Chair of the Conference - usually Gala Dinner)

- VIII. Take photos during the conference and submit them on your and IES Facebook profile.
 - IX. Submit your expenses report via Concur:

In Concur, please select the following expense report purpose (ERP).

Expense Report Purpose Lvl 1 - Technical Activities Societies

Expense Report Purpose Lvl 2 - Industrial Electronics Society

Expense Report Purpose Lvl 3 - VP-Membership Student Activities

Expense Report Purpose Lvl 4 - YPROS (this is the only option available to select)

If you have further questions, please check:

http://www.ieee-ies.org/members/treasurer-information

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IES operating unit team contact is Matt LaFleur.





- X. PLEASE NOTE THAT IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE is consist of:
 - Recognition Diploma
 - up to USD 1000 travel cost reimbursements.
- XI. You can find all the necessary information on Industry Electronics Society websites: https://www.facebook.com/IndustrialElectronicsSociety/ http://www.ieee-ies.org/SYP

On behalf of the IEEE IES-SYPA Competition Jury:

IEEE IES President Xinghuo Yu, IES Treasurer Milos Manic, and IES President-Elect Terry Martin,
Vice President for Conference Activities Juan José Rodríguez Andina,
Vice President for Membership Activities Yousef Ibrahim,
Conference General Chairs: Giovanni Petrone, Walter Zamboni
Web & Information Committee: Andres A. Nogueiras Melendez, Aleksander Malinowski,
Ad-Hoc committee related to IEEE OFAC Sanctions Programs:
Gus Wagner Director, Technical Activities Operations and Society Support Services IEEE Technical Activities.
Matt LaFleur Technical Community Program Coordinator IEEE Technical Activities.
and Young Professional & Student Activity Committee: Marek Turzynski, Hani Vahedi, Marek Jasinski.

Congratulations and Good Luck, Chair of the IEEE IES Young Professional & Student Activity Committee, Marek Jasinski